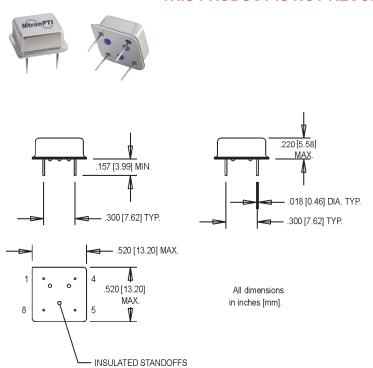
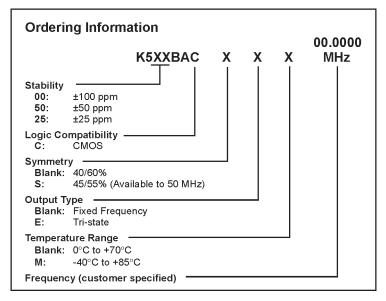


THIS PRODUCT IS NOT RECOMMENDED FOR NEW DESIGNS.





Pin Connection

PIN	FUNCTION				
1	N/C or Tri-state				
2	Ground				
3	Output				
4	+Vdd				

	PARAMETER	Symbol	Min.	Тур.	Max.	Units	Condition	
1 1	Frequency Range	F	1		70	MHz		
	Frequency Stability	∆F/F	(See Ordering Information)				See Note 1	
Electrical Specifications	Operating Temperature	TA	-40		+85	°C		
	Storage Temperature	Ts	-55		+125	°C		
	Input Voltage	Vdd	4.5	5.0	5.5	٧		
liji	Input Current	ldd			15	mA	<20 MHz	
) Sec					50	mA	20 - 70 Mhz	
	Symmetry (Duty Cycle)		40		60	%	@ 1.4V TTL/0.5Vcc CMOS	
rica	Rise/Fall Time	Tr/Tf						
ect	≤20 MHz				8	ns	TTL	
					10	ns	CMOS	
	>20 Mhz				6	ns	TTL	
					8	ns	CMOS	
	Fanout				10		TTL	
	Start up Time				10	ms		
	Temperature Cycle	MIL-STD-883, Method 1010, Condition B				-55°C to +125°C; Air-toAir; 100 cycles; 10 min. dwell		
	Mechanical Shock	MIL-STD-883, Method 2002, Condition B				1500 g's		
	Vibration	MIL-STD-883, Method 2007, Condition B				20-2000 Hz; 0.06 inch; 15 g's; 3 planes		
<u>e</u>	Humidity Steady State	MIL-STD-202, Method 103				40°C; 90%-95% R.H.; 56 days		
Environmental	Thermal Shock	MIL-STD-883, Method 1011.7, Condition B				100°C to 0°C; Water-to-Water; 15 cycles		
ਵੱ	Electrostatic Discharge	MIL-STD-883, Method 3015, Class II				2 KV to 4 KV Threshold		
ļ ķ	Solderability	MIL-STD-883, Method 2022.2				Solder dip; Meniscograph Criteria		
🖆	Hermeticity	MIL-STD-883, Method 1014.8, Condition A1				Mass spectro. 2 x 10-8 atoms. CC/sec He		
	Resistance to Soldering	MIL-STD-202, Method 210D, Condition J				235°C; 30 seconds		
	Lead Integrity	MIL-STD-883, Method 2004.5, Cond. A,B1				Lead tension & bend stress		
	Marking Permanence	MIL-STD-883, Method 2015.8				Resistance to solvents		
	Life Test	MIL-STD-	MIL-STD-883, Method 1005.6				125°C, powered, 1000 hours minimum	

MtronPTI reserves the right to make changes to the product(s) and service(s) described herein without notice. No liability is assumed as a result of their use or application.